V_{RRM} = 650 V Qc $I_F(\leq 160^{\circ}C) = 6$ = 1.39 V

SiC SBD P3D06006G2 650V SiC Schottky Diode



Features

- Qualified to AEC-Q101
- Ultra-Fast Switching
- Zero Reverse Recovery Current
- High-Frequency Operation
- Positive Temperature Coefficient on V_F
- High Surge Current
- 100% UIS tested

TO-263-2

Cathode	1
Anode	2



Standards Benefits

- Improve System Efficiency
- Reduction of Heat Sink Requirement
- Essentially No Switching Losses
- Parallel Devices Without Thermal Runaway



Application

- Consumer SMPS
- Boost Diodes in PFC or DC/DC Stages
- AC/DC Converters



Order Information

Part Number	Package	Marking
P3D06006G2	TO-263-2	P3D06006G2

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1. Maximum Ratings

At T_J= 25°C, unless specified otherwise

Parameter	Symbol	Value	Unit	Test condition
Repetitive Peak Reverse Voltage	V_{RRM}	650	V	T _C = 25℃
Surge Peak Reverse Voltage	V_{RSM}	650	V	T _C = 25°C
DC Blocking Voltage	V_{R}	650	V	T _C = 25°C
		21		T _C = 25°C
Forward Current	I _F	11	Α	T _C = 125°C
		6		T _C = 160°C
Repetitive Peak Forward		41		T _C = 25°C, t _p = 10ms
Surge Current	I _{FRM}	20	A	$T_C = 125$ °C, $t_p = 10$ ms
Non-Repetitive Forward		48		T_{C} = 25°C, t_{p} = 10ms
Surge Current	I _{FSM}	39	Α	T _C = 125°C, t _p = 10ms
Power Dissipation	P _{tot}	91	W	T _C = 25°C
Operating Junction and Storage Temperature	T _J , T _{STG}	-55 to +175	°C	
TO-220 Mounting Torque	_	1	Nm	
M3 Screw	T_{orq}	8.8	Ibf-in	

2. Thermal Characteristics

Parameter	Symbol	Values	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.65	%C/W

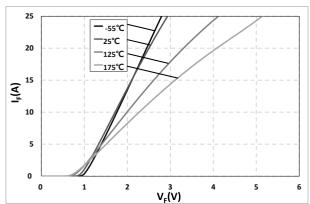
3. Electrical Characteristics

At T_J= 25°C, unless specified otherwise

			Values												
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test condition									
Forward Voltage	V	/ -	1.39	1.6	V	I _F = 6A, T _J = 25℃									
Forward Voltage	V _F		1.65	/		I _F = 6A, T _J = 175°C									
Reverse Current	I _R	/	3.8	30	μΑ	V _R = 650V, T _J = 25℃									
			255	/		V _R = 650V, T _J = 175°C									
		275 / 28 / pl			V _R = 0V, T _J = 25°C f= 1MHz										
Total Capacitance	re C		/	/	/	/	/	/	/	1	1	28	/	рF	V _R = 200V, T _J = 25°C f= 1MHz
				V _R = 400V, T _J = 25℃ f= 1MHz											
Total Capacitive Charge	Q _C	/	14.4	/	nC	$V_R = 400V, I_F = 6A$ $T_J = 25^{\circ}C$									
Capacitance Stored Energy	E _C	/	1.76	/	μЈ	V _R = 400V									

4. Typical Performance

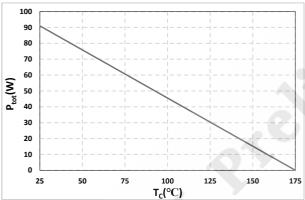
At T_J= 25°C, unless specified otherwise



1000
1000
175°C
1
1
25°C
-55°C
-55°C
V_R(V)

Fig. 1 Typical Forward Characteristics $I_F = f(V_F)$; $T_J = -55^{\circ}C$, $25^{\circ}C$, $125^{\circ}C$, $175^{\circ}C$

Fig. 2 Reverse Characteristics $I_R=f(V_R)$; $T_J=-55$ °C, 25°C, 125°C, 175°C



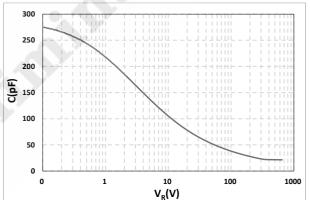
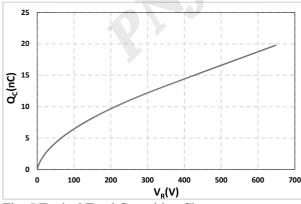


Fig. 3 Typical Power Derating $P_{tot} = f(T_C)$

Fig. 4 Typical Total Capacitance $C=f(V_R)$



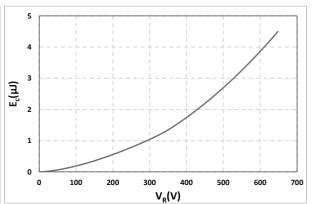
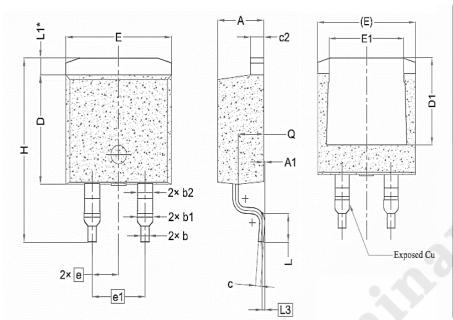


Fig. 5 Typical Total Capacitive Charge $Q_C = f(V_R)$

Figure 6. Capacitance Stored Energy $E_C = f(V_R)$

5. Package Outlines



e da 4	DIMENSIONS				
SYMBOL	MIN.	NOM,	MAX,		
Α	4.24	4.44	4.64		
A1	0.00	0.10	0.25		
b	0,70	0,80	0,90		
b1	1.20	1.55	1.75		
b2	1,20	1.45	1.70		
С	0,40	0,50	0,60		
c2	1,15	1,27	1,40		
D	8.82	8.92	9.02		
D1	6,86	7,65	_ \		
E	9.96	10.16	10.36		
E1	6.89 7.77		7.89		
е	2.54 BSC				
e1	5.08 BSC				
Н	14.61	15.00	15.88		
L	1,78 2,32		2,79		
L1	1.36 REF.				
L3	0.25 BSC				
Q	2,30 2,48 2,70				

Drawing and dimensions